

10 AMP SILICON BRIDGE RECTIFIERS

ACTUAL SIZE

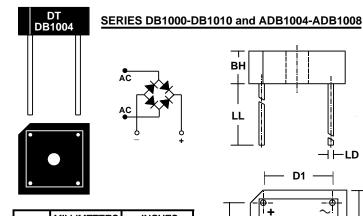
FEATURES

- VOID FREE VACUUM DIE SOLDERING FOR MAXIMUM • MECHANICAL STRENGTH AND HEAT DISSIPATION (Solder Voids: Typical < 2%, Max. < 10% of Die Area)
- **BUILT-IN STRESS RELIEF MECHANISM FOR** SUPERIOR RELIABILITY AND PERFORMANCE
- SURGE OVERLOAD RATING TO 300 AMPS PEAK
- RECOGNIZED FILE #E124962

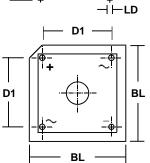
MECHANICAL DATA

- Case: Molded plastic, U/L Flammability Rating 94V-0 •
- Terminals: Round silver plated copper pins .
- Soldering: Per MIL-STD 202 Method 208 guaranteed •
- · Polarity: Marked on side of case; positive lead at beveled corner
- Mounting Position: Any. Through hole provided for #6 screw •
- Weight: 0.18 Ounces (5.4 Grams) ٠

MECHANICAL SPECIFICATION



SYM	MILLIM	IETERS	INCHES					
	MIN	MAX	MIN	MAX				
BL	18.5	19.6	0.73	0.77				
BH	6.4	7.6	0.25	0.3				
D1	12.2	13.2	0.48	0.52				
LL	22.2	n/a	0.875	n/a				
LD	1.2	1.3	0.048	0.052				



MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.

PARAMETER (TEST CONDITIONS)		RATINGS										
					NON-CONTROLLED AVALANCHE						UNITS	
Series Number		ADB 1004	ADB 1006	ADB 1008	DB 1000	DB 1001	DB 1002	DB 1004	DB 1006	DB 1008	DB 1010	
Maximum DC Blocking Voltage	Vrм		600	800	50				600		1000	
Working Peak Reverse Voltage	Vrwm											
Maximum Peak Recurrent Reverse Voltage												
RMS Reverse Voltage	VR (RMS)	280	420	560	35	70	140	280	420	560	700	
Power Dissipation in V(BR) Region for 100 μS Square Wave	Ркм	500			n/a							WATTS
Continuous Power Dissipation in V(BR) Region @ THs=80° C (Heat Sink Temp)	Pr	2			n/a							
Thermal Energy (Rating for Fusing)	l²t	64									AMPS ² SEC	
Peak Forward Surge Current. Single 60Hz Half-Sine Wave Superimposed on Rated Load (JEDEC Method). TJ = 150° C	IFSM	300									AMPS	
Average Forward Rectified Current @ Tc = 50° C (Notes 1, 3) @ Ta = 50° C (Note 2)	lo	10 8										
Junction Operating and Storage Temperature Range	Тј, Тѕтс	-55 to +150								°C		
Minimum Avalanche Voltage	V(BR) Min	See Note 4		n/a								
Maximum Avalanche Voltage		See Note 4			n/a							VOLTS
Maximum Forward Voltage (Per Diode) at 5 Amps DC		0.95 (Typ. 0.90)									1	
Maximum Reverse Current at Rated VRM @ TA = 25° C @ TA = 100° C		1 50								μΑ		
Minimum Insulation Breakdown Voltage (Circuit to Case)		2000								VOLTS		
Typical Thermal Resistance Junction to Ambient (Note 2) Junction to Case (Note 1)	RθJA RθJC	12 5								°C/W		

NOTES: (1) Bridge mounted on 5.1" x 4.3" x 0.11" thick (12.9cm x 10.8cm x 0.3cm) aluminum plate

(2) Bridge mounted on PC Board with 0.5" sq. (12mm sq.) copper pads and bridge lead length of 0.375" (9.5mm)
(3) Bolt bridge on heat sink with #6 screw, using silicon thermal compound between bridge and mounting surface for maximum heat transfer.
(4) These bridges exhibit the avalanche characteristic at breakdown. If your application requires a specific breakdown voltage range, please contact us.



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RATING & CHARACTERISTIC CURVES FOR SERIES DB1000 - DB1010 and SERIES ADB1004 - ADB1008

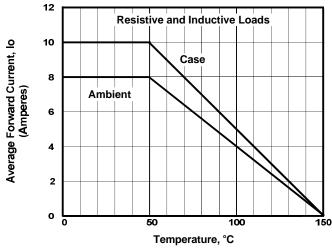
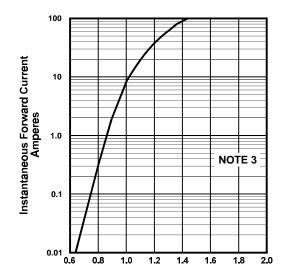
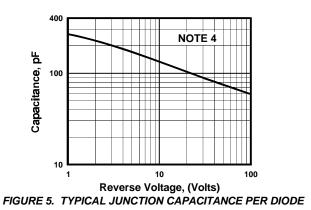
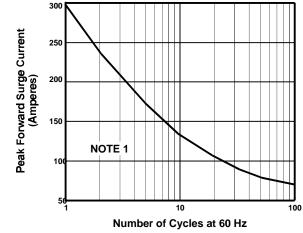


FIGURE 1. FORWARD CURRENT DERATING CURVE

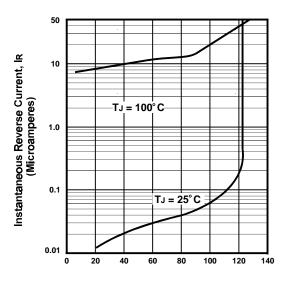


Instantaneous Forward Voltage (Volts) FIGURE 3. TYPICAL FORWARD CHARACTERISTIC PER DIODE









Percent of Rated Peak Reverse Voltage FIGURE 4. TYPICAL REVERSE CHARACTERISTICS

NOTES

(1) Case Temperature, Tc, With Bridge Mounted on 5.1" x 4.3" x 0.11" Thick (12.9cm x 10.8cm x 0.3cm) Aluminum Plate

Ambient Temperature, TA, With Bridge Mounted on PC Board With 0.5" Sq. (12mm Sq.) Copper Pads And Bridge Lead Length of 0.375" (9.5mm)

- (2) TJ = 150° C
- (3) TJ = 25°C; Pulse Width = 300µSec; 1% Duty Cycle
- (4) TJ = 25°C; f = 1 MHz; Vsig = 50mVp-p